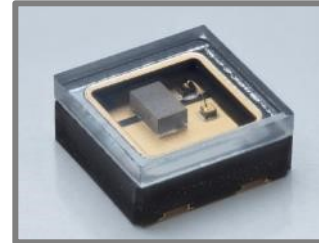


UV LED Chip in SMD Flat-top Package

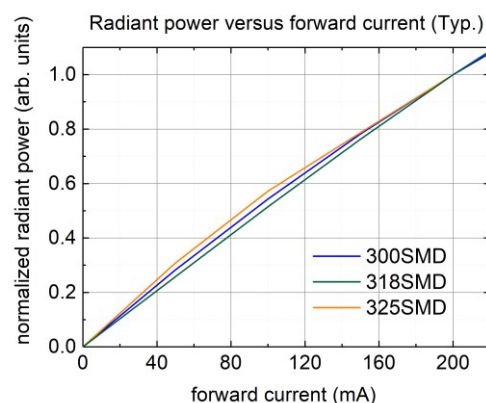
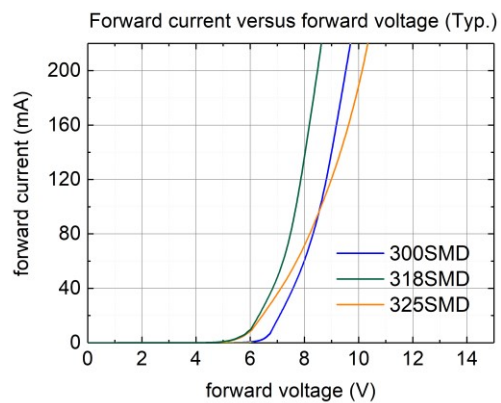
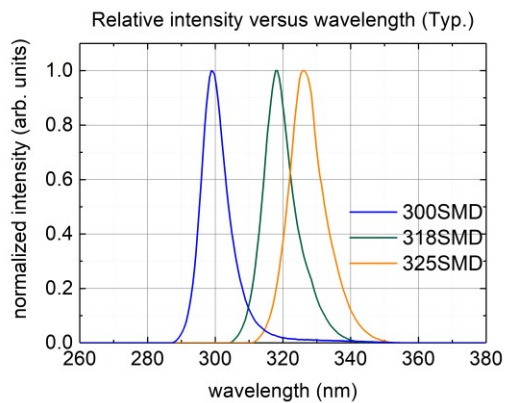
Wavelengths: 300 nm – 325 nm

Optical and electrical characteristics



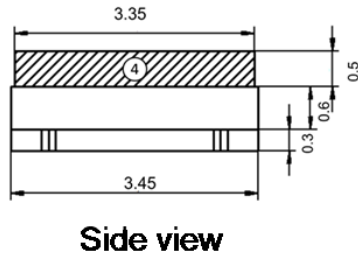
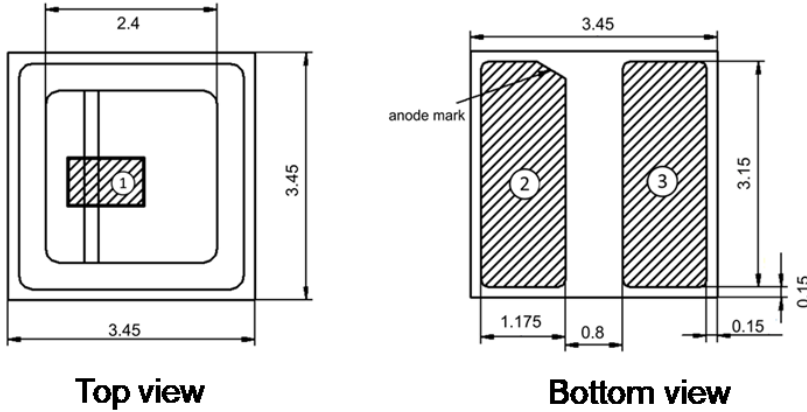
($I_F = 200 \text{ mA}$, $T_{amb} = 20^\circ\text{C}$)

Parameter	Unit	300SMD			318SMD			325SMD		
		Min.	Typ.	Max.	Min.	Typ.	Max.	Min.	Typ.	Max.
Peak wavelength	nm	295	300	305	315	318	323	322	325	328
Full width at half maximum	nm	9	11	14	12	15	18	12	15	18
Forward voltage	V	7.5	9	12	8	10	12	8	10	13
Radiant power	mW	15	20	24	12	15	18	8	10	12



Mechanical dimensions

(All dimensions in mm)



No.	Part name	Material
1	LED chip	AlGaIn/ sapphire
2	anode	Au
3	cathode	Au
4	sealing glass	quartz

Note:

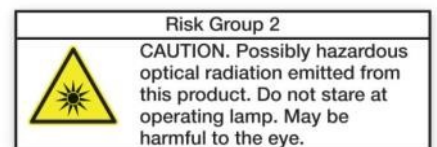
LED chips designed for flip-chip bonding i.e. light is extracted through the transparent substrate.

Customization:

- Wavelength customization between 230 nm and 330 nm on request.
- SMD and TO-39 packages can be developed on request.

Handling precautions:

- LEDs are sensitive to static electricity.
- Use of ESD protection during handling is strongly recommended.



More information at www.uvphotonics.de or contact us at info@uvphotonics.de.